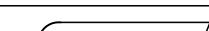


1		2		3		4		5		6	
D			MASTER DRAWING								
	CONTROL (IPC-6012)		<input type="checkbox"/> CLASS 1 <input checked="" type="checkbox"/> CLASS 2 <input type="checkbox"/> CLASS 3								
	DESIGN (IPC-2221)		Type 1 <input type="checkbox"/> Single-Sided    Type 2 <input checked="" type="checkbox"/> Double-Sided Type 3 <input type="checkbox"/> Multilayer without Blind or Buried Vias Type 4 <input type="checkbox"/> Multilayer with Blind or Buried Vias								
	BOARD DETAILS		Dimension (mm) : 74.00 X 57.00 (+/- 0.20 mm) <input checked="" type="checkbox"/> Panelisation    Number of PCB per Panel : - Panel dimension (mm) : -    X - (+/- 0.20 mm) <input type="checkbox"/> V-Cut (Scoring) : - <input type="checkbox"/> Tab Routing (mm) : - Number of Layers : 2 <input checked="" type="checkbox"/> Controlled impedance (see Note1) (IPC-TM-650) Minimum track width (mm) : 0,20 Minimum clearance (mm) : 0,106								
C	VIA Level : <input type="checkbox"/> A <input checked="" type="checkbox"/> B <input type="checkbox"/> C Finished hole size		Minimum hole (mm) : 0.20    External pad diameter (mm) : 0.70 Etchback max (µm) : 20    Internal pad diameter (mm) : -								
	MATERIAL (IPC-4101/99)		<input checked="" type="checkbox"/> All Materials used must be RoHS COMPLIANT <input checked="" type="checkbox"/> Lead-Free FR4 <input checked="" type="checkbox"/> TG mini : 150 °C <input checked="" type="checkbox"/> Flame resistance UL-94 : V-0    Moisture Absorption : <0.15%								
	BASE COPPER THICKNESS		External :    MidLayer :    InternalPlane : <input checked="" type="checkbox"/> 17.50µm (1/2 oz.) <input type="checkbox"/> 17.50µm (1/2 oz.) <input type="checkbox"/> 17.50µm (1/2 oz.) <input type="checkbox"/> 35µm (1 oz.) <input type="checkbox"/> 35µm (1 oz.) <input type="checkbox"/> 35µm (1 oz.) <input type="checkbox"/> 70µm (2oz.) <input type="checkbox"/> 70µm (2oz.) <input type="checkbox"/> 70µm (2oz.) <input type="checkbox"/> Other (see Stackup) <input type="checkbox"/> Other (see Stackup) <input type="checkbox"/> Other (see Stackup)								
	PCB THICKNESS		<input type="checkbox"/> 0.80mm <input checked="" type="checkbox"/> 1.60 mm <input type="checkbox"/> Other (mm) : - Thickness tolerance (%) : 10    (see Stackup)								
B	BOARD FINISH		<input checked="" type="checkbox"/> ENIG - Electroless Nickel Immersion Gold (IPC-4552) <input type="checkbox"/> HAL Lead Free <input type="checkbox"/> HAL Sn/Pb <input type="checkbox"/> Electrolytic Gold <input type="checkbox"/> Number of Fingers : -    Gold Fingers Chamfer : <input type="checkbox"/> Electrolytic Gold (Ni 7 à 11µm, Au 1 à 1.5µm) <input type="checkbox"/> 20° <input type="checkbox"/> 30° <input type="checkbox"/> 45° <input type="checkbox"/> Flash (Ni 3 à 10µm, Au 0.2 à 0.4µm)								
	Gold Fingers										
	Silkscreen		<input type="checkbox"/> None <input checked="" type="checkbox"/> Top <input checked="" type="checkbox"/> Bottom Colour : <input checked="" type="checkbox"/> White <input type="checkbox"/> Other : -								
	Solder Mask (IPC-SM-840)		<input type="checkbox"/> None <input checked="" type="checkbox"/> Photoimageable <input checked="" type="checkbox"/> Gloss <input type="checkbox"/> Matte Colour : <input checked="" type="checkbox"/> Green <input type="checkbox"/> Other : -    Logo Manufacturer : <input checked="" type="checkbox"/> Date Code Marking <input checked="" type="checkbox"/> UL94V0 Marking <input checked="" type="checkbox"/> None <input type="checkbox"/> Yes Type : <input checked="" type="checkbox"/> B1 <input checked="" type="checkbox"/> B2 <input type="checkbox"/> T <input type="checkbox"/> H <input checked="" type="checkbox"/> Keep original file for all opening								
A	SMD COMPONENTS Paste Mask		<input type="checkbox"/> None <input checked="" type="checkbox"/> Top <input type="checkbox"/> Bottom <input checked="" type="checkbox"/> Pitch mini (mm) : 0.50 <input type="checkbox"/> BGA Pitch mini (mm) : - <input checked="" type="checkbox"/> Paste Mask without reduction unless otherwise specified Number Fiducial Target <input checked="" type="checkbox"/> On PCB <input checked="" type="checkbox"/> Top : 2 <input type="checkbox"/> Bottom : - <input checked="" type="checkbox"/> On Panel <input checked="" type="checkbox"/> Top : 3 <input type="checkbox"/> Bottom : -								
	PCB TEST		<input checked="" type="checkbox"/> Electrical Test, coverage 100%, 2 sides (IPC-9252) <input checked="" type="checkbox"/> Test coupons to test controlled impedance Card TEST <input checked="" type="checkbox"/> X-RAY For Pitch ≤ 0.65mm and BGA								
Important : The locating holes must be drilled at the same time as the other holes © Polygone CAO - COPY FORBIDDEN WITHOUT AUTHORIZATION											



[No Variations]		Polygone CAO	AF2007-016	M. JULLIG	21/08/2020	M. LAURY
VARIANT		COMPAGNY	NUMERO AF	PCB DESIGNER	DATE	CHECKED BY
	STMicroelectronics 12 Rue Jules Horowitz 38019 Grenoble France	TITLE <b>STM32WB35 QFN48</b>				
		REF. <b>MB1715A</b>	LAYER <b>Bottom Assembly</b>			REF.
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